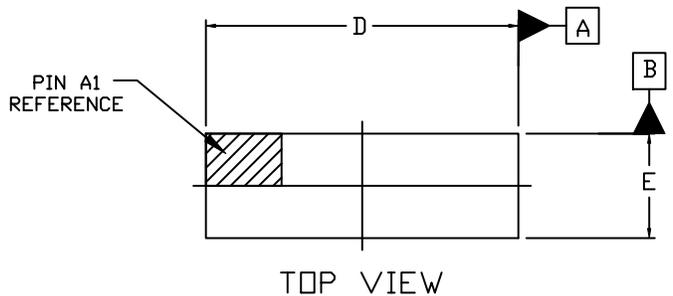




SCALE 4:1

WLCSP27, 3.89x1.30, 0.4P
CASE 567NJ
ISSUE A

DATE 22 SEP 2020

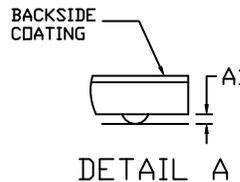


TOP VIEW

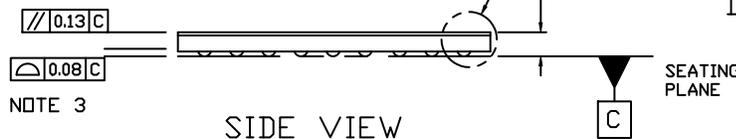
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

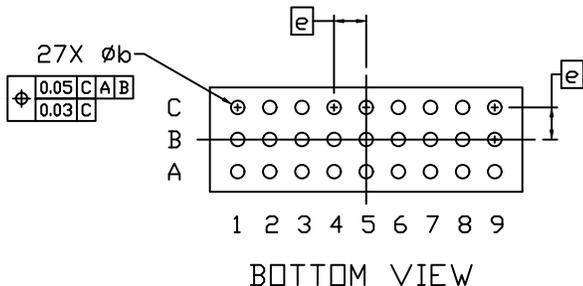
DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	---	---	0.33
A1	0.04 REF		
b	0.12	0.17	0.22
D	3.84	3.89	3.94
E	1.25	1.30	1.35
e	0.40 BSC		



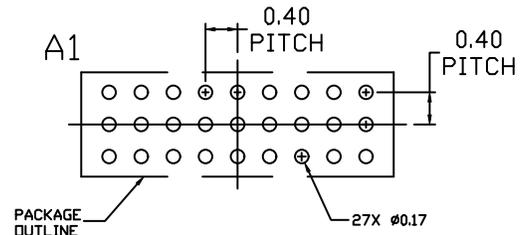
DETAIL A



SIDE VIEW



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the [DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D](#).

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DESCRIPTION:	WLCSP27, 3.89X1.30, 0.4P	PAGE 1 OF 1

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